

PRODUCT/PROCESS CHANGE NOTICE (PCN)								
PCN #: PA141 Product Affected	MEANS OF DISTINGUISHING CHANGED DEVICES:  ■ Product Mark Change in ordering part#  □ Back Mark □ Date Code							
Date Effective:	February 11, 2015 IDT PCN DESK		Other		Yes	□ No		
Contact: E-mail:	pcndesk@idt.cor	Attachment:  Yes No  Samples:  Please contact your local sales representative for sample request.						
☐ Die Technolog ☐ Wafer Fabrica ☐ Assembly Pro ☐ Equipment ☐ Material ☐ Testing ☐ Manufacturing ☐ Data Sheet	tion Process cess	This notification is to advise will be changed to revision B.  The new die revision is fully.  There is no change to therma.  This is no change to the die to IDT requests customers to us	our customers of a silicon die revision. The current die revision A B with a change in the orderable part number and device top mark. It hardware and specification compatible with the previous revision. It has all and MSL specification due to this die revision. It technology or process. The die change is minor. It is B revision in their newer design/projects and switch existing as soon as possible. Last time buy for revision A will be on					
CUSTOMER ACTION TO BE ACTION.	cate that you require l or request addition d that this change is	/process.  ENT OF RECEIPT: e written notification of this ch al information. If IDT does no acceptable. version manufactured after the	t receive ack	nowledgem	ent within 30	days of this notice		
Customer:	•		Appro	val for sh	ipments pr	ior to effective date.		
		Mail Address:						
Title: Pho		one # /Fax #:						
CUSTOMER CO	OMMENTS:							
IDT ACKNOWI	LEDGMENT OF I	RECEIPT:						
RECD. BY:			DATE: _					



## PRODUCT/PROCESS CHANGE NOTICE (PCN)

### ATTACHMENT I - PCN #: PA1410-01

**PCN Type:** Die Revision Change

**Data Sheet Change:** No

**Detail of Change:** 

This notification is to advise our customers of a silicon die revision. The current die revision A will be changed to revision B with a change in the orderable part number and device top mark.

Revision B has the following improvements and design enhancements/features:

- 1) Significant EMI improvement.
- 2) More reliable EEPROM booting.
- 3) Increased design margins.
- 4) Better manufacturing yield and testability
- 5) Increased over current trip level to avoid unnecessary over-current limiting that may happen with unusual loads.

The new die revision is fully hardware and specification compatible with the previous revision.

There is no change to thermal and MSL specification due to this die revision.

This is no change to the die technology or process. The die change is minor.

IDT requests customers to use B revision in their newer design/projects and switch existing design/projects to B revision as soon as possible. Last time buy for revision A will be on February 11, 2015.

#### Table 1

Old Ordering Part Number	New Ordering Part Number
P9036-0NTGI	P9036BNTGI
P9036-0NTGI8	P9036BNTGI8
P9036A-0NTGI	P9036BNTGI
P9036A-0NTGI8	P9036BNTGI8



# **Qualification Report**

Date: 10/28/2014

**Product Type:** IDTP9036B (Wireless Power Transmitter)

Device Family:AW571T005ZNAProcess Technology:0.25um, 40V BCD

Package Type:NTG48 (QFN)Fab Location:TSMC, Taiwan

Test Description	Conditions	Sample Size	Reject	Comments
Device Characterization	IDT's datasheet conditions	33	0	Pass
ESD: Human Body Model	JESD22-A114 (JS-001) Classification	3	0	Pass
ESD: Charged Device Model	JESD22-C101 Classification	3	0	Pass
Latch-Up	JESD78	3	0	Pass
Temperature Cycling	JESD22-A104, -55°C to 125°C, 700 cycles	25 x 1 lot	0	Pass <sup>1</sup>
High Temperature Storage Life	JESD22-A103, +150 °C, 1000 hrs	25 x 1 lot	0	Pass <sup>1</sup>
Highly Accelerated Temperature and Humidity Stress (Biased)	JESD22-A110, +130 °C, 85% R.H., Vcc max, 100 hrs	25 x 1 lot	0	Pass <sup>1</sup>
Moisture Classification	J-STD-020	25 x 2 lots	0	Pass <sup>1</sup>
Data Retention	JESD47G-01	1 wafer	0	Pass <sup>1</sup>
Read Cycle	JESD47G-01	1 wafer	0	Pass <sup>1</sup>

Note 1: Qualification by similarity of product IDTP9030